



LINALG

Release Notes

Applies to Product Release: 1.2.0
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Contents

Overview.....	1
Label and Version Information for the Release	1
Software Label Information.....	1
Hardware Support	1
New and Updated Features.....	2
New Features	2
BLAS	2
Known Issues	2
Limitations.....	2
Licensing.....	2
Delivery Package	2
Source Code Components	2
Object Code Components.....	3
Required Compile Tools	3
Tools Supplied by Texas Instruments.....	3
Customer Documentation List	3

LINALG 1.2.0

Overview

This document provides information on the features, functions, delivery package, compile tools, licensing, and incident report (IR) resolutions incorporated in the following release of software: **LINALG 1.2.0**. It includes a list of the known issues that are present at the time of this release.

Label and Version Information for the Release

This release supports the following software and hardware versions.

Software Label Information

Table 1 lists the software label and code versions applicable to this release.

Table 1 Labels and Versions Supported by this Release

Release	Label/Version Information
LINALG	DEV.LINALG.01.02.00.00

Hardware Support

This release is supported on the following hardware platform:

- 66AK2H
- C6678
- AM572x

New and Updated Features

This release provides support for the following new and updated features.

New Features

The following new features are supported in this release.

BLAS

- Can be used in DSP-only applications

Known Issues

Table 2 provides information on IRs that are known issues for this release.

Table 2 Known Issue IRs for this Release

IR Parent/ Child Number	Severity Level	IR Description	Notes
SDOCM122339	Minor	CLAPACK tests have failures	CLAPACK testing results are almost identical to the testing results when running CLAPACK test suite on x86 with Ubuntu.
SDOCM122341	Minor	BLAS accelerator wrapper C version not tested	In MCSDK-HPC environment, C++ compiler is used to compile the BLAS wrapper code.

Limitations

The following is a list of known limitations for this release.

- LAPACK is not available for DSP-only platforms.

Licensing

Refer to LINALG Software Manifest document.

Delivery Package

LINALG 1.2.0 from Texas Instruments will be delivered with the Processor-SDK Linux and Processor-SDK RTOS distribution.

Source Code Components

The following components are provided as source code.

- BLIS
- CBLAS
- TICBLAS

- CLAPACK
- BLASBLISACC
- Tuning and examples

Object Code Components

The following components are provided as binary object code.

- BLIS, CBLAS, and TICBLAS for C66x DSP
- BLIS, CBLAS, TICBLAS, CLAPACK, BLASBLISACC for Cortex-A15

Required Compile Tools

Specific tools and patches must be used to compile and/or deploy Texas Instruments software. Texas Instruments cannot guarantee product performance when other tools are used.

Tools Supplied by Texas Instruments

All TI supplied tools for compiling LINALG are installed when Processor-SDK is installed.

Customer Documentation List

Table 3 lists the documents that are accessible to users of LINALG.

Table 3 Product Documentation included with this Release

Document #	Document Title	File Name
1	Read Me	readme.txt
2	LINALG Software Manifest	LINALG_1.2.0_manifest.html
3	Release Notes	LINALG_1.2.0_release_notes.pdf